

## Publikationen

Werner Bogner, Johannes Jakob, R. Weigel, Franz Xaver Röhrl, Stefan Zorn (2019): Bare die connections via aerosol jet technology for millimeter wave applications. In: International Journal of Microwave and Wireless Technologies, vol. 11, no. Special Issue 5-6 (EuMW 2018 Special Issue (Part I)) [June], pp. 441-446. DOI: 10.1017/S1759078719000114.

Werner Bogner, Franz Xaver Röhrl, Felix Sepaintner, Stefan Zorn, Andreas Scharl (2019): Simulation and Manufacturing of Low Loss PCB Structures with Additional Electromagnetic Field in Air. In: Proceedings of the IEEE MTT-S International Microwave Workshop Series on Advanced Materials and Processes (IMWS-AMP) [July 16-18, 2019; Bochum].

Werner Bogner, Johannes Jakob, R. Sammer, Franz Xaver Röhrl, Stefan Zorn (2019): WR12 to planar transmission line transition on organic substrate. In: Proceedings of the 49th European Microwave Conference (EuMC)/European Microwave Week (EuMW) 2019 (September 29-October 4, 2019; Paris, France).

Werner Bogner, Johannes Jakob, R. Weigel, Franz Xaver Röhrl, Stefan Zorn (2018): Bare Die Connections via Aerosol Jet Technology for Millimeter Wave Applications. In: Proceedings of the 48th European Microwave Conference (EuMC)/European Microwave Week (EuMW) 2018 (September 24-28, 2018; Madrid, Spain).

Werner Bogner, Johannes Jakob, R. Weigel, U. Hassel, Roman Sammer, Franz Xaver Röhrl, Stefan Zorn (2017): Cost-Effective SIW Band-Pass Filters for Millimeter Wave Applications. In: Proceedings of the 47th European Microwave Conference (EuMC)/European Microwave Week (EuMW) 2017 (October 8-12, 2017, Nürnberg). DOI: 10.23919/EuMC.2017.8230878.

Werner Bogner, Johannes Jakob, Franz Xaver Röhrl, Stefan Zorn, D. Hageneder (2016): Differential Wideband Interconnects for Organic Millimeter Wave Chip Packages. An effort to design an all-purpose RF chip package. In: Proceedings of the 11th European Microwave Integrated Circuits Conference 2016 (October 03-04 2016, London, UK).

Werner Bogner, Johannes Jakob, Franz Xaver Röhrl, Stefan Zorn, D. Hageneder (2016): Differential Wideband Interconnects for Organic Millimeter Wave Chip Packages. An effort to design an all-purpose RF chip package. In: Proceedings of the 46th European Microwave Conference (EuMC)/European Microwave Week (EuMW) 2016 (October 03-07 2016, London, UK).

T. Dietl, Franz Xaver Röhrl (2015): Thermisches Management für Leiterplatten-basierte Hochfrequenz-Packages. In: PLUS - Fachzeitschrift für Aufbau und Verbindungstechnik in der Elektronik: Produktion von Leiterplatten und Systemen, no. Dezember.

Werner Bogner, Johannes Jakob, Franz Xaver Röhrl, D. Hageneder (2015): Wideband RF interconnects for organic chip packages comparison of single ended and differential transitions. An effort to design an all-purpose RF chip package. In: Proceedings of the 45th European Microwave Conference (EuMC)/European Microwave Week (EuMW) 2015 (September 06-11 2015, Paris, France).

Werner Bogner, Johannes Jakob, R. Sammer, Franz Xaver Röhrl, Stefan Zorn: WR12 to planar transmission line transition on organic substrate. Invited Talk. In: 49th European Microwave Conference (EuMC), Paris, Frankreich.

Werner Bogner, Franz Xaver Röhrl, Felix Sepaintner, Stefan Zorn, Andreas Scharl: Simulation and Manufacturing of Low Loss PCB Structures with Additional Electromagnetic Field in Air. Invited Talk. In: IEEE MTT-S International Microwave Workshop Series on Advanced Materials and Processes (IMWS-AMP), Bochum.

Werner Bogner, Johannes Jakob, Siegfried Hildebrand, Franz Xaver Röhrl, Stefan Zorn: Projekt NePUMuk (Neue digitale Produktions- und Mikrostrukturierungstechnologien für Anwendungen bis 80 GHz). Projektbericht.